



# SOT1430-1

plastic extremely thin small outline package; no leads; 10 terminals; body 1.6 x 1.3 x 0.33 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	X2QFN
<b>Package type industry code</b>	X2QFN10
<b>Package style descriptive code</b>	XSON (extremely thin small outline; no leads)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	10-2-2015

Table 1. Package summary

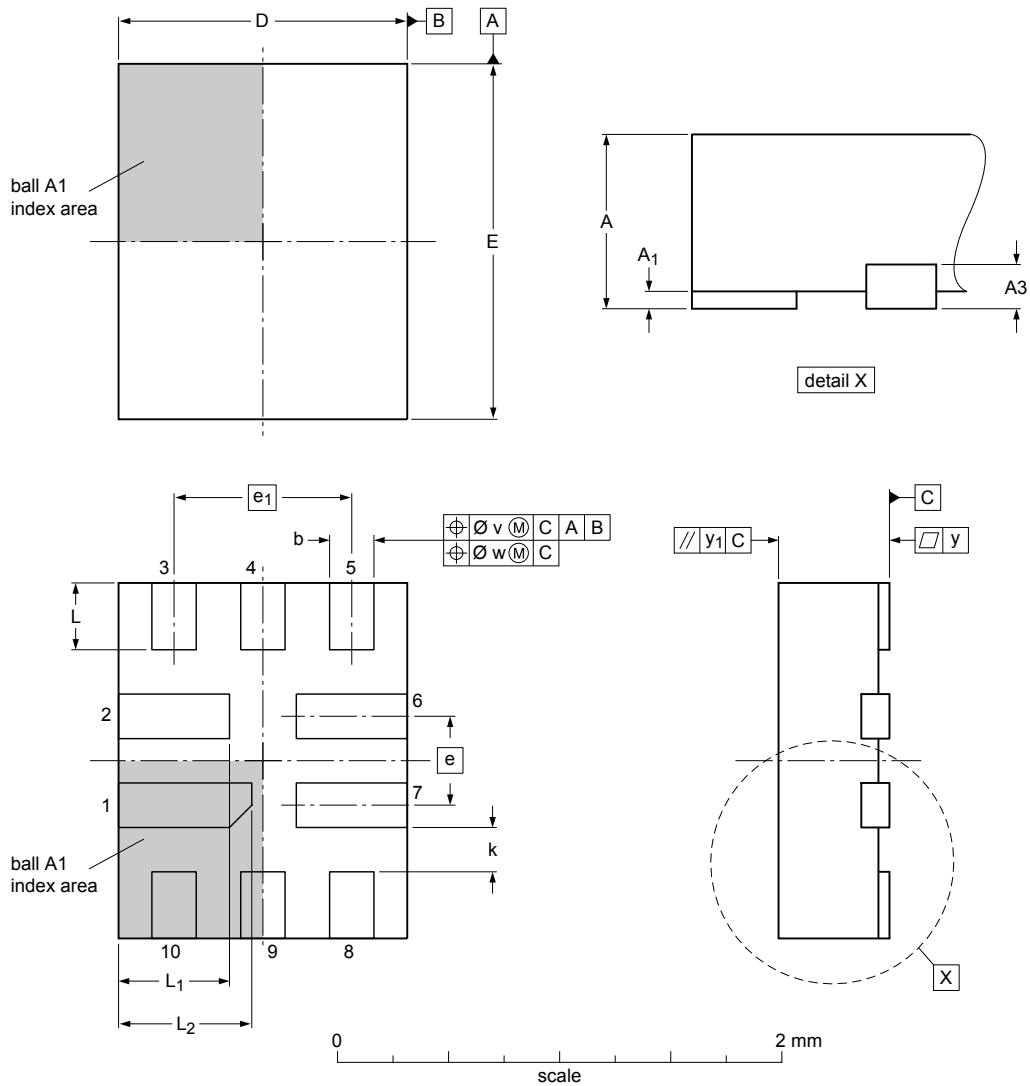
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.25	-	1.3	1.35	mm
E	package width	1.55	-	1.6	1.65	mm
A	seated height	-	-	-	0.33	m
e	nominal pitch	-	-	0.4	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	10	-	



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## 2. Package outline

X2QFN10: plastic extremely thin small outline package; no leads; 10 terminals; body 1.6 x 1.3 x 0.33 mm SOT1430-1



Dimensions (mm are the original dimensions)

Unit <sup>(1)</sup>	A	A <sub>1</sub>	A <sub>3</sub>	b	D	E	e	e <sub>1</sub>	k	L	L <sub>1</sub>	L <sub>2</sub>	v	w	y	y <sub>1</sub>
max	0.33	0.05		0.25	1.35	1.65				0.35	0.55	0.65				
mm nom			0.100	0.20	1.30	1.60	0.4	0.8		0.30	0.50	0.60	0.10	0.05	0.05	0.05
min		0.00		0.15	1.25	1.55			0.15	0.25	0.45	0.55				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1430-1		MO-288			-14-12-16- 15-02-10

Fig. 1. Package outline X2QFN10 (SOT1430-1)

plastic extremely thin small outline package; no leads; 10 terminals; body 1.6 x 1.3 x 0.33 mm

### 3. Legal information

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